

RoHS Compliant Product  
 A suffix of "-C" specifies halogen & lead-free

## DESCRIPTION

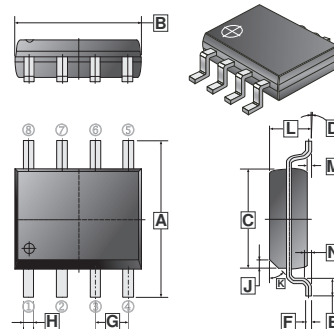
Advanced Power MOSFETs provide the designers with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

SOP-8 package is widely preferred for commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters.

## FEATURES

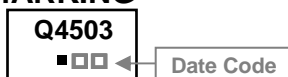
- Low R<sub>DS(ON)</sub> Provides Higher Efficiency and Longer Battery Life
- Low Thermal Impedance Copper Lead Frame
- Fast Switching Speed
- High Performance Trench Technology

### SOP-8



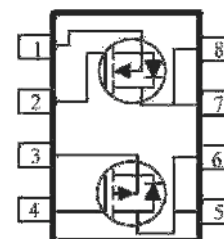
REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	5.79	6.20	H	0.33	0.51
B	4.70	5.11	J	0.375 REF.	
C	3.80	4.00	K	45° REF.	
D	0°	8°	L	1.3	1.752
E	0.40	1.27	M	0	0.25
F	0.10	0.25	N	0.25 REF.	
G	1.27 TYP.				

## MARKING



## PACKAGE INFORMATION

Package	MPQ	Leader Size
SOP-8	4K	13 inch



## ORDER INFORMATION

Part Number	Type
SSG4503J-C	Lead (Pb)-free and Halogen-free

## ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub>=25°C unless otherwise specified)

Parameter	Symbol	Ratings		Unit	
		N-CH	P-CH		
Drain-Source Voltage	V <sub>DS</sub>	30	-30	V	
Gate-Source Voltage	V <sub>GS</sub>	±20		V	
Continuous Drain Current <sup>1</sup>	I <sub>D</sub>	T <sub>A</sub> =25°C	6.9	-6.3	A
		T <sub>A</sub> =70°C	5.5	-5	A
Pulsed Drain Current <sup>2</sup>	I <sub>DM</sub>	20	-20	A	
Total Power Dissipation	P <sub>D</sub>	1.4		W	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	150, -55~150		°C	
Thermal Resistance Ratings					
Thermal Resistance from Junction-Ambient	R <sub>θJA</sub>	89		°C/W	

**N-Ch ELECTRICAL CHARACTERISTICS** (T<sub>A</sub>=25°C unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	-	-	V	V <sub>GS</sub> =0, I <sub>D</sub> =250μA
Gate Threshold Voltage	V <sub>GS(th)</sub>	1	1.5	3	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA
Gate-Body Leakage Current	I <sub>GSS</sub>	-	-	±100	nA	V <sub>DS</sub> =0, V <sub>GS</sub> = ±20V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	-	-	1	μA	V <sub>DS</sub> =30V, V <sub>GS</sub> =0
Drain-Source On-Resistance <sup>3</sup>	R <sub>DS(ON)</sub>	-	10	28	mΩ	V <sub>GS</sub> =10V, I <sub>D</sub> =6A
		-	14	42		V <sub>GS</sub> =4.5V, I <sub>D</sub> =4A
Forward Transfer conductance	g <sub>fs</sub>	4	-	-	S	V <sub>DS</sub> =10V, I <sub>D</sub> =6A
Diode Forward Voltage <sup>3</sup>	V <sub>SD</sub>	-	-	1.2	V	V <sub>GS</sub> =0, I <sub>S</sub> =1.7A
Total Gate Charge <sup>3</sup>	Q <sub>g</sub>	-	13.5	-	nC	V <sub>DS</sub> =24V V <sub>GS</sub> =4.5V I <sub>D</sub> =6A
Gate-Source Charge	Q <sub>gs</sub>	-	1.4	-		
Gate-Drain Charge	Q <sub>gd</sub>	-	4.7	-		
Turn-on Delay Time <sup>3</sup>	T <sub>d(on)</sub>	-	5	-	nS	V <sub>DS</sub> =20V V <sub>GS</sub> =10V R <sub>D</sub> =20Ω R <sub>G</sub> =3.3Ω I <sub>D</sub> =1A
Rise Time	T <sub>r</sub>	-	8	-		
Turn-off Delay Time	T <sub>d(off)</sub>	-	18.5	-		
Fall Time	T <sub>f</sub>	-	9	-		
Input Capacitance	C <sub>iss</sub>	-	770	-	pF	V <sub>DS</sub> =25V V <sub>GS</sub> =0 f=1MHz
Output Capacitance	C <sub>oss</sub>	-	80	-		
Reverse Transfer Capacitance	C <sub>rss</sub>	-	75	-		

**P-Ch ELECTRICAL CHARACTERISTICS** (T<sub>A</sub>=25°C unless otherwise specified)

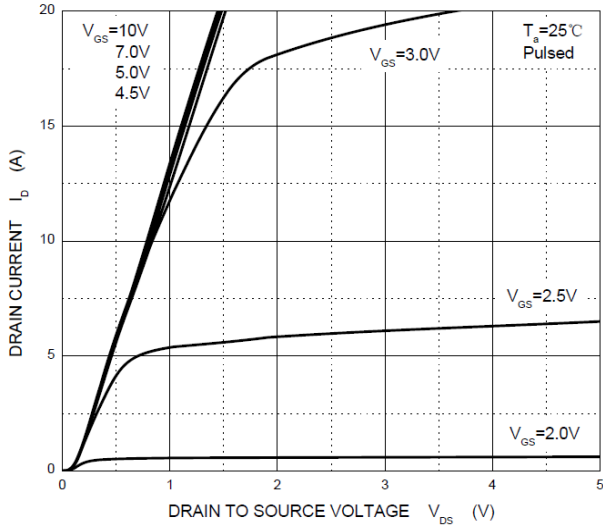
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-30	-	-	V	V <sub>GS</sub> =0, I <sub>D</sub> = -250μA
Gate Threshold Voltage	V <sub>GS(th)</sub>	-1	-1.7	-3	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> = -250μA
Gate-Body Leakage Current	I <sub>GSS</sub>	-	-	±100	nA	V <sub>DS</sub> =0, V <sub>GS</sub> = ±20V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	-	-	-1	μA	V <sub>DS</sub> = -30V, V <sub>GS</sub> =0
Drain-Source On-Resistance <sup>3</sup>	R <sub>DS(ON)</sub>	-	16	36	mΩ	V <sub>GS</sub> = -10V, I <sub>D</sub> = -6A
		-	25	55		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -4A
Forward Transfer conductance	g <sub>fs</sub>	4	-	-	S	V <sub>DS</sub> = -10V, I <sub>D</sub> = -6A
Diode Forward Voltage <sup>3</sup>	V <sub>SD</sub>	-	-	-1.2	V	V <sub>GS</sub> =0, I <sub>S</sub> = -1.7A
Total Gate Charge <sup>3</sup>	Q <sub>g</sub>	-	20	-	nC	V <sub>DS</sub> = -24V V <sub>GS</sub> = -4.5V I <sub>D</sub> = -6A
Gate-Source Charge	Q <sub>gs</sub>	-	2	-		
Gate-Drain Charge	Q <sub>gd</sub>	-	7	-		
Turn-on Delay Time <sup>3</sup>	T <sub>d(on)</sub>	-	8	-	nS	V <sub>DS</sub> = -15V V <sub>GS</sub> = -10V R <sub>D</sub> =15Ω R <sub>G</sub> =3.3Ω I <sub>D</sub> = -1A
Rise Time	T <sub>r</sub>	-	7	-		
Turn-off Delay Time	T <sub>d(off)</sub>	-	34	-		
Fall Time	T <sub>f</sub>	-	26	-		
Input Capacitance	C <sub>iss</sub>	-	1380	-	pF	V <sub>DS</sub> = -25V V <sub>GS</sub> =0 f=1MHz
Output Capacitance	C <sub>oss</sub>	-	150	-		
Reverse Transfer Capacitance	C <sub>rss</sub>	-	140	-		

Notes:

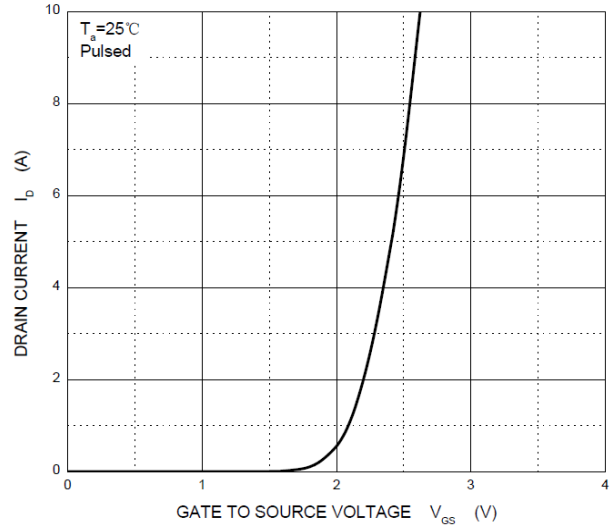
1. These tests are performed with infinite heat sink.
2. Pulse width by Max. junction temperature.
3. Pulse Test: Pulse width ≤ 300μs, duty cycle ≤ 2%.

**N-Ch CHARACTERISTIC CURVES**

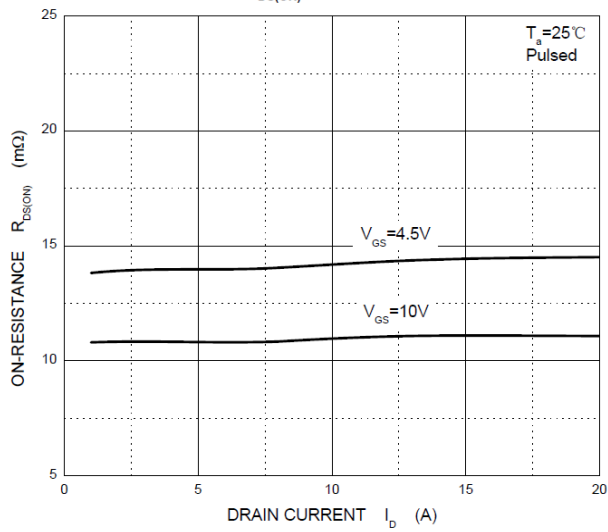
**Output Characteristics**



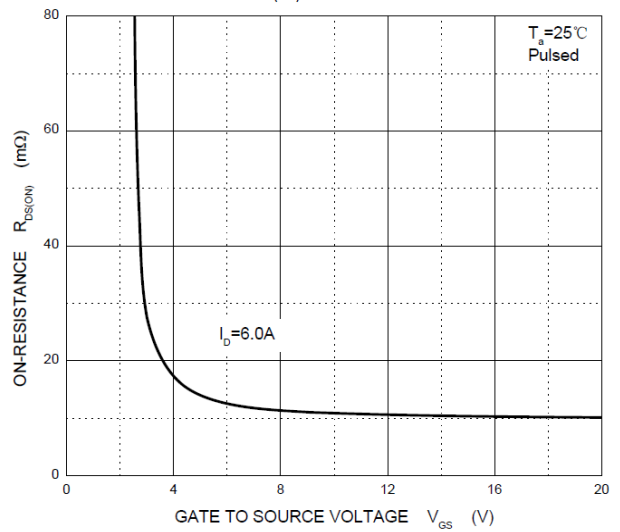
**Transfer Characteristics**



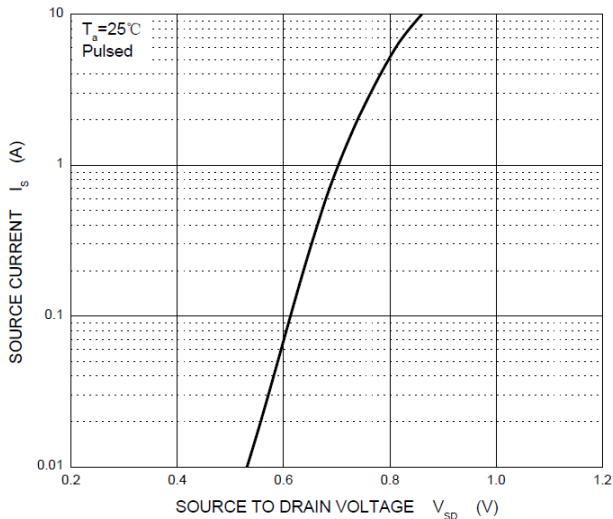
$R_{DS(ON)}$  —  $I_D$



$R_{DS(ON)}$  —  $V_{GS}$

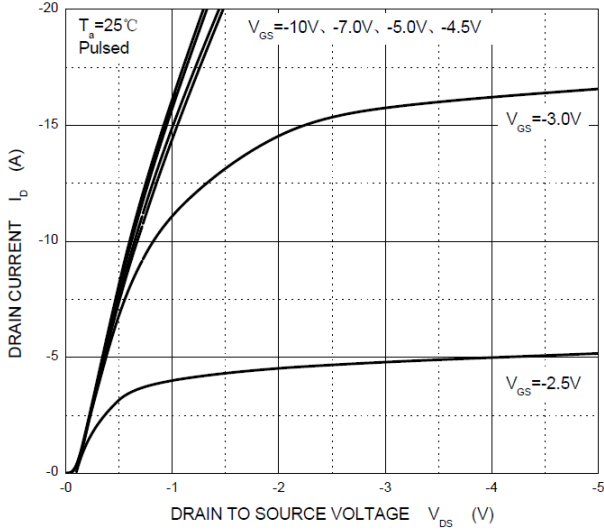


$I_S$  —  $V_{SD}$

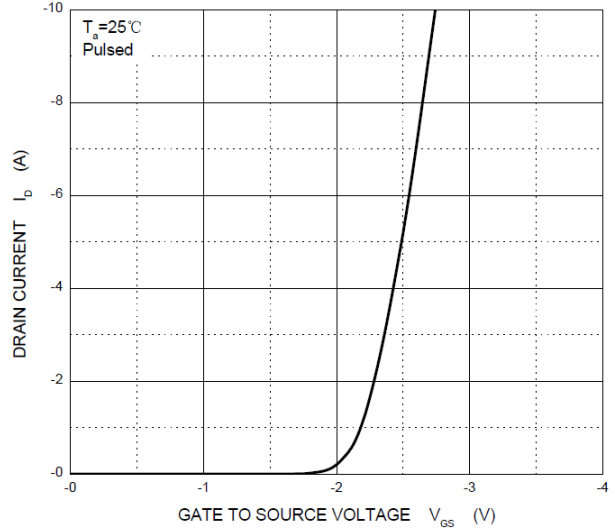


**P-Ch CHARACTERISTIC CURVES**

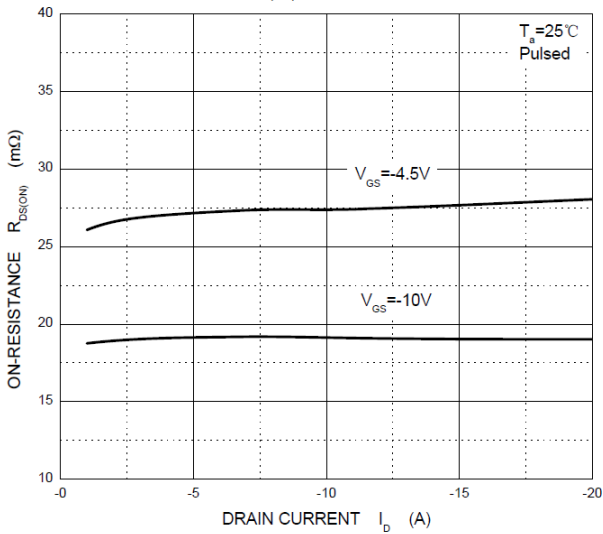
Output Characteristics



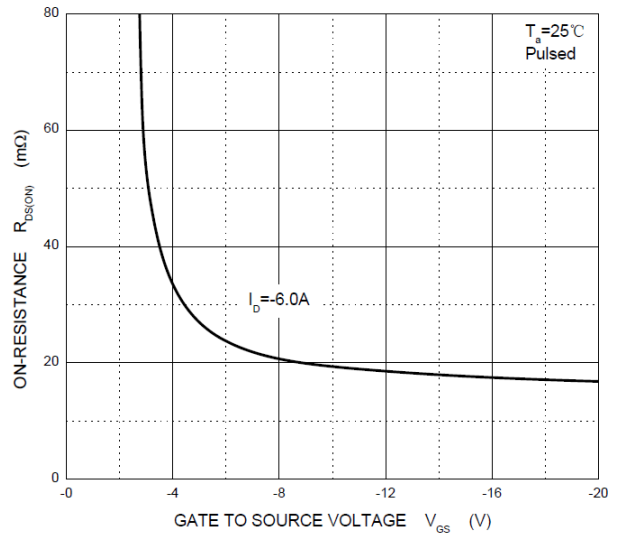
Transfer Characteristics



$R_{DS(ON)}$  —  $I_D$



$R_{DS(ON)}$  —  $V_{GS}$



$I_S$  —  $V_{SD}$

